

HAT2044R

Silicon N Channel Power MOS FET Power Switching

REJ03G1170-0300

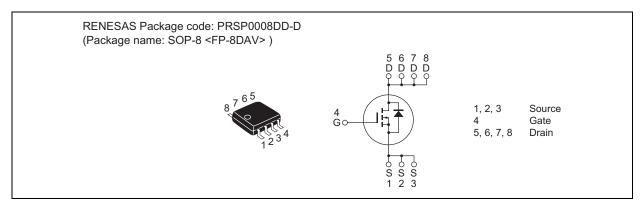
(Previous: ADE-208-722A)

Rev.3.00 Sep 07, 2005

Features

- Capable of 2.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance $R_{DS (on)} = 6.5 \text{ m}\Omega \text{ typ (at } V_{GS} = 4.5 \text{ V)}$

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	30	V
Gate to source voltage	V _{GSS}	±12	V
Drain current	I _D	15	Α
Drain peak current	I _{D (pulse)} Note 1	120	Α
Body-drain diode reverse drain current	I _{DR}	15	Α
Channel dissipation	Pch Note 2	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

Electrical Characteristics

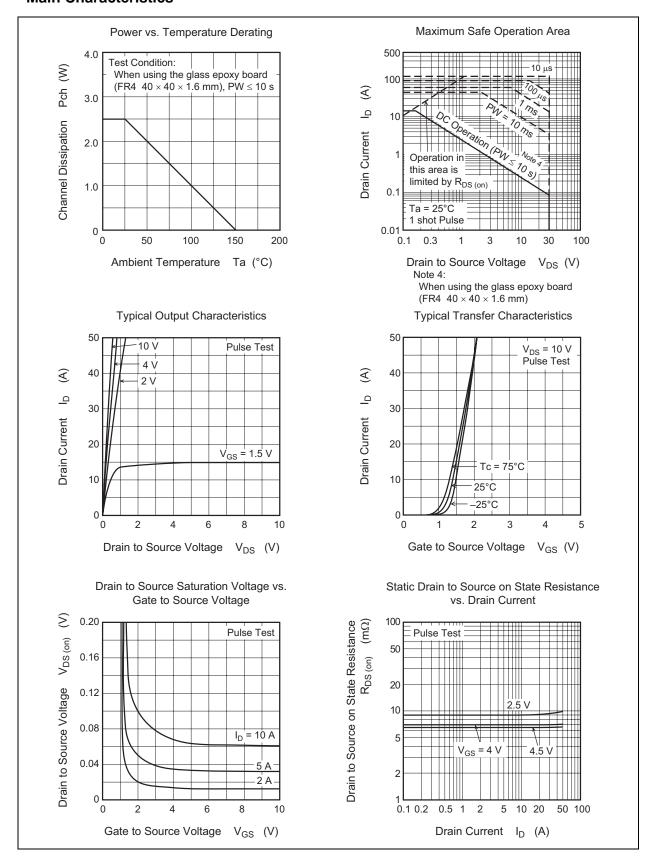
 $(Ta = 25^{\circ}C)$

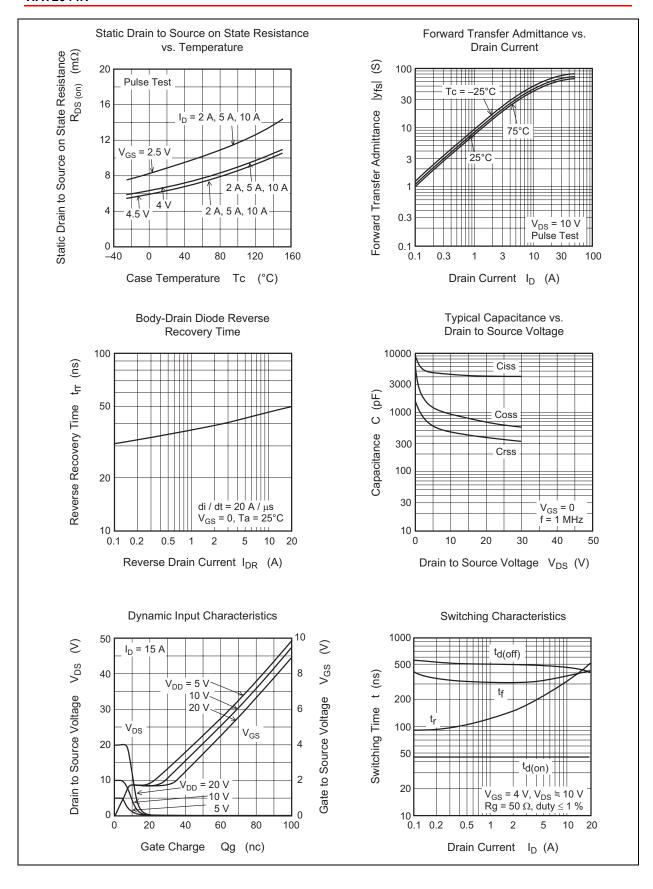
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	30	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}			±0.1	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}			1	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	0.4		1.4	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}		6.5	9.0	mΩ	$I_D = 8 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}		7.0	9.5	mΩ	$I_D = 8 \text{ A}, V_{GS} = 4.0 \text{ V}^{\text{Note } 3}$
	R _{DS (on)}	_	9.0	13.0	mΩ	$I_D = 8 \text{ A}, V_{GS} = 2.5 \text{ V}^{\text{Note } 3}$
Forward transfer admittance	y _{fs}	24	40	_	S	$I_D = 8 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	3420	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	950	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	480	_	pF	f = 1 MHz
Total gate charge	Qg	_	48	_	nC	V _{DD} = 10 V
Gate to source charge	Qgs	_	32	_	nC	$V_{GS} = 4 V$
Gate to drain charge	Qgd	_	16	_	nC	I _D = 15 A
Turn-on delay time	t _{d (on)}	_	45	_	ns	$V_{GS} = 4 \text{ V}, I_D = 8 \text{ A},$
Rise time	t _r	_	285	_	ns	V _{DD} ≅ 10 V
Turn-off delay time	t _{d (off)}	_	470	_	ns	
Fall time	t _f	_	360	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.85	1.1	V	$I_F = 15 \text{ A}, V_{GS} = 0^{\text{Note 3}}$
Body-drain diode reverse recovery time	t _{rr}	_	45	_	ns	I _F = 15 A, V _{GS} = 0
						di _F /dt = 20 A/μs

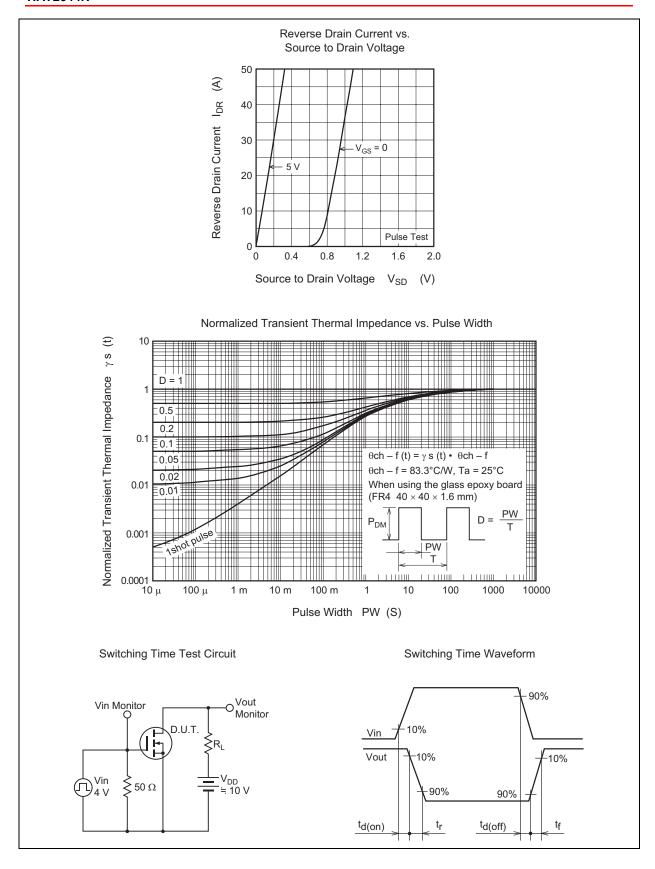
Note: 3. Pulse test

^{2.} When using the glass epoxy board (FR4 $40\times40\times1.6$ mm), PW ≤10 s

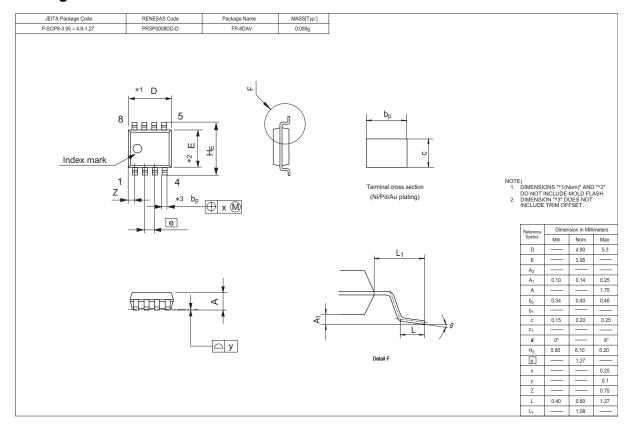
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2044R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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